

100V, 4A, High-Frequency Half-Bridge Gate Driver

DESCRIPTION

The MP1917A is a high-frequency, half-bridge, N-channel power MOSFET driver. Its low-side and high-side driver channels are controlled independently and matched with less than 5ns of time delay. Under-voltage lockout (UVLO) on both the high-side and low-side supplies forces the outputs low in the event that the supply is insufficient. The integrated bootstrap diode reduces the external component count.

The MP1917A is available in a QFN-10 (4mmx4mm) package.

FEATURES

- Drives an N-Channel MOSFET Half-Bridge
- 115V Bootstrap Voltage Range
- On-Chip Bootstrap Diode
- Typical Propagation Delay of 20ns
- Gate Driver Matching of Less than 5ns
- Drives a 2.2nF Load with 15ns of Rise Time and 12ns of Fall Time at 12V VDD
- TTL-Compatible Input
- Quiescent Current of Less than 150µA
- UVLO for Both High-Side and Low-Side **Gate Drivers**
- QFN-10 (4mmx4mm) Package

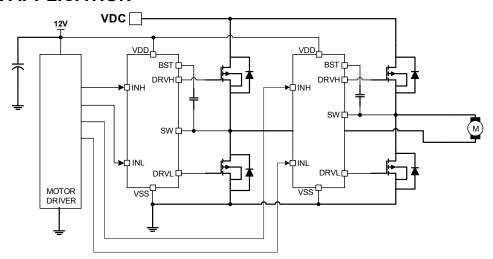
APPLICATIONS

- Isolated Brick Power
- Telecom Half-Bridge Power Supplies
- Avionics DC/DC Converters
- **Two-Switch Forward Converters**
- **Active Clamp Forward Converters**

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TYPICAL APPLICATION

7/25/2019





ORDERING INFORMATION

Part Number	Package	Top Marking
MP1917AGR*	QFN-10 (4mmx4mm)	See Below

^{*} For Tape & Reel, add suffix –Z (e.g. MP1917AGR–Z).

TOP MARKING

MPSYWW

M1917A

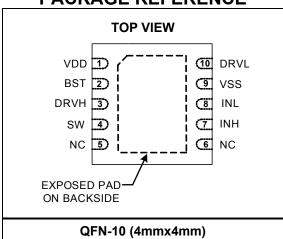
LLLLLL

MPS: MPS prefix Y: Year code WW: Week code

M1917A: First six digits of the part number

LLL: Lot number

PACKAGE REFERENCE





ABSOLUTE MAXIMUM RATINGS (1)
Supply voltage (V _{DD})0.3V to 18V
SW voltage (V _{SW})
1V (-18V for < 100nS) to 105V BST voltage (V _{BST})0.3V to 115V
BST to SW0.3V to 18V
DRVH to SW
0.3V (-2V for < 100nS) to (BST - SW) + $0.3V$
DRVL to VSS
0.3V (-2V for < 100nS) to $(V_{DD} + 0.3V)$
All other pins
Continuous power dissipation ($T_A = 25^{\circ}C$) (2) QFN-10 (4mmx4mm)2.66W
Junction temperature
Lead temperature
Storage temperature65°C to 150°C
Recommended Operating Conditions (3)
Supply voltage (V _{DD})
SW voltage (V _{SW})1.0V to 98V
SW slew rate<50V/ns
Operating junction temp (T _J)40°C to 125°C

Thermal Resistance (4)	$oldsymbol{ heta}_{JA}$	$\boldsymbol{\theta}_{JC}$	
QFN-10 (4mmx4mm)	47	7	°C/W
NOTES:			

- 1) Exceeding these ratings may damage the device.
- The maximum allowable power dissipation is a function of the maximum junction temperature T_J (MAX), the junction-to-ambient thermal resistance θ_{JA}, and the ambient temperature T_A. The maximum allowable continuous power dissipation at any ambient temperature is calculated by P_D (MAX) = (T_J (MAX) T_A) / θ_{JA}. Exceeding the maximum allowable power dissipation produces an excessive die temperature, causing the regulator to go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- The device is not guaranteed to function outside of its operating conditions.
- 4) Measured on JESD51-7, 4-layer PCB.



ELECTRICAL CHARACTERISTICS

 V_{DD} = V_{BST} - V_{SW} = 12V, V_{SS} = V_{SW} = 0V, no load at DRVH and DRVL, T_A = +25°C, unless otherwise noted.

Parameter	Symbol	Condition	Min	Тур	Max	Units
Supply Currents						
VDD quiescent current	I _{DDQ}	INL = INH = 0		100	150	μΑ
VDD operating current	I _{DDO}	fsw = 500kHz		9		mA
Floating driver quiescent current	I _{BSTQ}	INL = INH = 0		60	90	μΑ
Floating driver operating current	I _{BSTO}	fsw = 500kHz		7.5		mA
Leakage current	I _{LK}	BST = SW = 100V		0.05	1	μΑ
Inputs						
INL/INH high				2	2.4	V
INL/INH low			1	1.4		V
INL/INH internal pull-down	Rin			185		kΩ
resistance	IXIN			100		K22
Under-Voltage Protection						
VDD rising threshold	V_{DDR}		6.4	6.8	7.2	V
VDD hysteresis	V_{DDH}			0.5		V
BST-SW rising threshold	V _{BSTR}		6.1	6.5	6.9	V
BST-SW hysteresis	V _{BSTH}			0.5		V
Bootstrap Diode						
Bootstrap diode VF at 100µA	V _{F1}			0.5		V
Bootstrap diode VF at 100mA	V _{F2}			0.95		V
Bootstrap diode dynamic R	R_D	At 100mA		2.5		Ω
Low-Side Gate Driver						
Low-level output voltage	Voll	I _O = 100mA		0.1		V
High-level output voltage to rail	Vohl	I _O = -100mA		0.36		V
Source current (5)	Іонь	$V_{DRVL} = 0V$, $V_{DD} = 12V$		3		Α
Source current (%)		$V_{DRVL} = 0V, V_{DD} = 16V$		4.7		Α
Sink current (5)	I _{OLL}	$V_{DRVL} = V_{DD} = 12V$		4.5		Α
Sink current (9)		$V_{DRVL} = V_{DD} = 16V$		6		Α
Floating Gate Driver						
Low-level output voltage	V _{OLH}	I _O = 100mA		0.1		V
High-level output voltage to rail	V _{ОНН}	I _O = -100mA		0.32		V
Source current (5)	1	$V_{DRVH} = 0V, V_{DD} = 12V$		2.6		Α
Source current (%)	Іонн	V _{DRVH} = 0V, V _{DD} = 16V		4		Α
Sink current (5)	la	$V_{DRVH} = V_{DD} = 12V$		4.5		Α
Sink current (5)	Іогн	$V_{DRVH} = V_{DD} = 16V$		5.9		Α



ELECTRICAL CHARACTERISTICS (continued)

V_{DD} = V_{BST} - V_{SW} = 12V, V_{SS} = V_{SW} = 0V, no load at DRVH and DRVL, T_A = +25°C, unless otherwise noted.

Parameter	Symbol	Condition	Min	Тур	Max	Units	
Switching Specification - Low-S	Switching Specification – Low-Side Gate Driver						
Turn-off propagation delay INL falling to DRVL falling	T_DLFF			20		ns	
Turn-on propagation delay INL rising to DRVL rising	T _{DLRR}			20			
DRVL rise time		C _L = 2.2nF		15		ns	
DRVL fall time		C _L = 2.2nF		15		ns	
Switching Specification – Floating	ng Gate D	river					
Turn-off propagation delay INH falling to DRVH falling	T_{DHFF}			20		ns	
Turn-on propagation delay INH rising to DRVH rising	T_{DHRR}			20		ns	
DRVH rise time		C _L = 2.2nF		15		ns	
DRVH fall time		C _L = 2.2nF		15		ns	
Switching Specification – Match	ing						
Floating driver turn-off to low-side driver turn-on (5)	T _{MON}			1	5	ns	
Low-side driver turn-off to floating driver turn-on (5)	T _{MOFF}			1	5	ns	
Minimum input pulse width that changes the output (5)	T_PW				50	ns	
Bootstrap diode turn-on or turn-off time (5)	T _{BS}			10		ns	
Thermal shutdown				150		°C	
Thermal shutdown hysteresis				25		°C	

NOTE:

⁵⁾ Guaranteed by design.

V_{BSTH} (mV)

. V_{ррн}

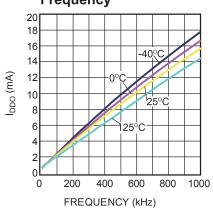
PROPAGATION DELAY (ns)



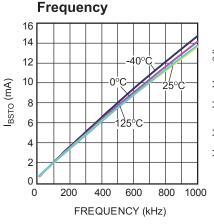
TYPICAL PERFORMANCE CHARACTERISTICS

 V_{DD} = 12V, V_{SS} = V_{SW} = 0V, T_A = +25°C, unless otherwise noted.

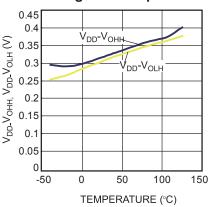
IDDO Operation Current vs. Frequency



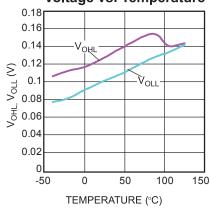
I_{BSTO} Operation Current vs. Frequency



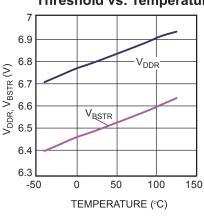
High-Level Output Voltage vs. Temperature



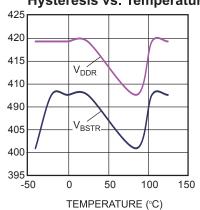
Low-Level Output Voltage vs. Temperature



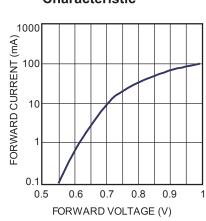
Under-Voltage Lockout Threshold vs. Temperature



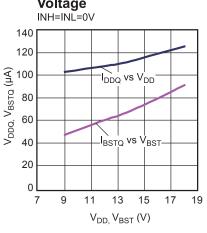
Under-Voltage Lockout Hysteresis vs. Temperature



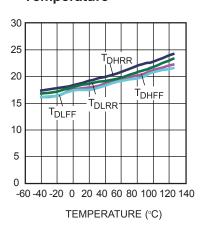
Bootstrap Diode I-V Characteristic



Quiescent Current vs. Voltage



Propagation Delay vs. Temperature



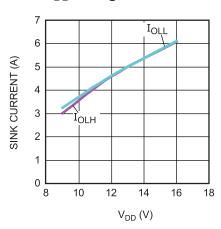
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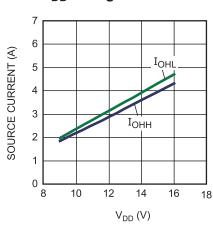
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

 V_{DD} = 12V, V_{SS} = V_{SW} = 0V, T_A = +25°C, unless otherwise noted.

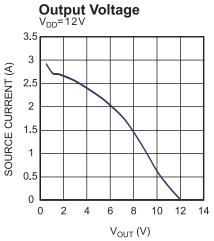
Sink Current vs. **V_{DD}** Voltage



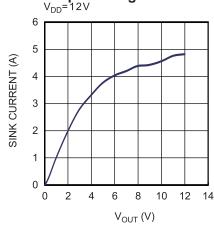
Source Current vs. V_{DD} Voltage



Source Current vs.



Sink Current vs. Output Voltage





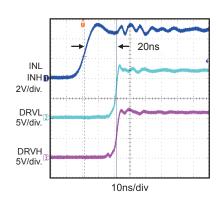
TYPICAL PERFORMANCE CHARACTERISTICS (continued)

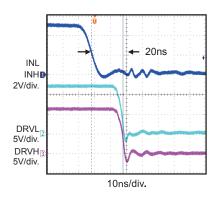
 V_{DD} = 12V, V_{SS} = V_{SW} = 0V, T_A = +25°C, unless otherwise noted.

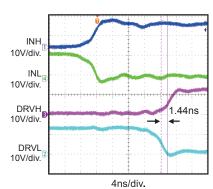
Turn-On Propagation Delay

Turn-Off Propagation Delay

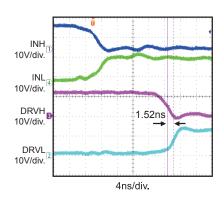
Gate Drive Matching T_{MOFF}



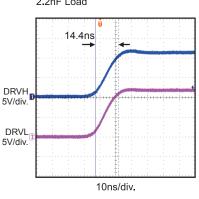




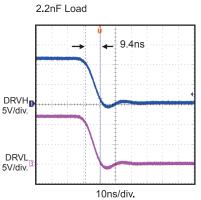
Gate Drive Matching T_{MON}



Drive Rise Time 2.2nF Load



Drive Fall Time





PIN FUNCTIONS

Pin#	Name	Description			
1	VDD	Supply input. VDD supplies power to the internal circuitry. Place a decoupling capacitor on ground close to VDD to ensure a stable and clean supply.			
2	BST	Bootstrap. Positive power supply for the internal floating high-side MOSFET driver. Connect a bypass capacitor between BST and SW.			
3	DRVH	Floating driver output.			
4	SW	Switching node.			
5, 6	NC	No connection.			
7	INH	Control signal input for the floating driver.			
8	INL	Control signal input for the low-side driver.			
9	VSS, exposed pad	Chip ground. Connect the exposed pad to VSS for proper thermal operation.			
10	DRVL	Low-side driver output.			



TIMING DIAGRAM

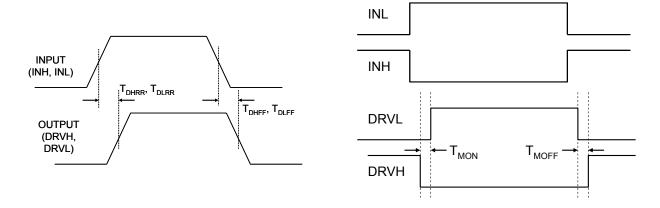


Figure 1: Timing Diagram



FUNCTIONAL BLOCK DIAGRAM

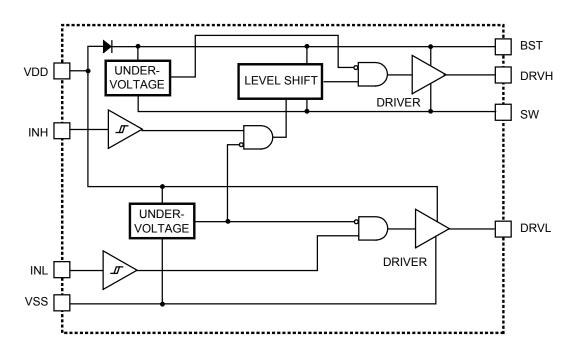


Figure 2: Functional Block Diagram



APPLICATION INFORMATION

The INH and INL input signals can be controlled independently. If both INH and INL control the high-side and low-side MOSFETs of the same bridge, set a sufficient dead time between INH

and INL low, and vice versa, to avoid shootthrough (see Figure 3). Dead time is defined as the time interval between INH low and INL low.

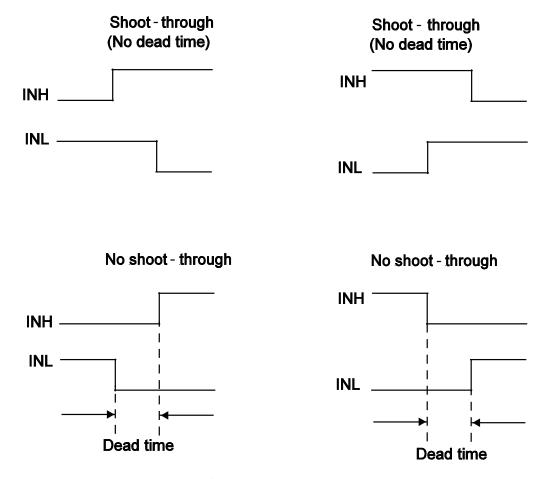


Figure 3: Shoot-Through Timing Diagram



REFERENCE DESIGN CIRCUITS

Half-Bridge Converter

The MP1917A drives the MOSFETS with alternating signals with dead time in half-bridge converter topology. The input voltage can rise up

to 100V with the alternating signals INT and INL coming from the PWM controller (see Figure 4).

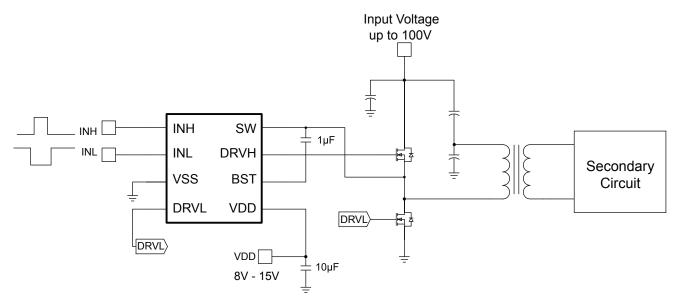


Figure 4: Half-Bridge Converter

Two-Switch Forward Converter

In two-switch forward converter topology, both MOSFETs are turned on and off simultaneously. The INH and INL input signals come from a PWM controller that senses the output voltage and output current during current-mode control.

The Schottky diodes clamp the reverse swing of the power transformer, and must be rated for the input voltage. The input voltage can rise up to 100V (see Figure 5).

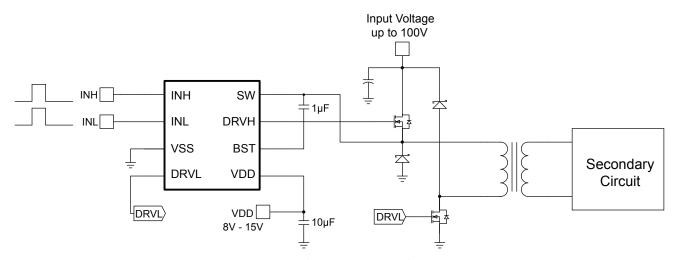


Figure 5: Two-Switch Forward Converter



Active Clamp Forward Converter

In active clamp forward converter topology, the MP1917A drives the MOSFETs with alternating signals. The high-side MOSFET, in conjunction with C_{reset}, is used to reset the power transformer with minimal power loss.

This topology is optimal for running at duty cycles exceeding 50%. The device may not be able to run at 100V under this topology (see Figure 6).

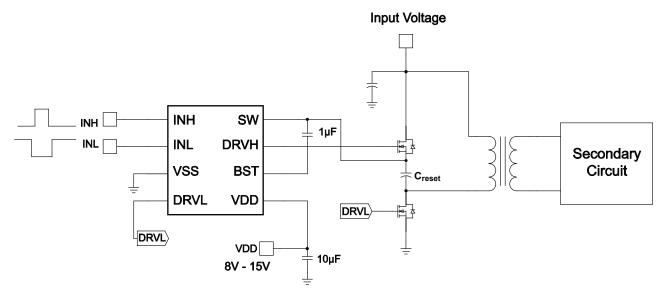
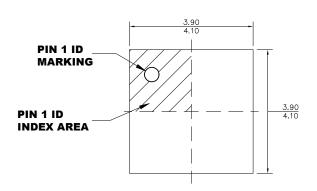


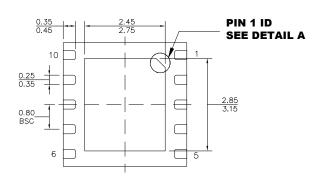
Figure 6: Active Clamp Forward Converter



PACKAGE INFORMATION

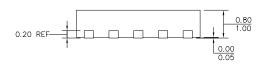
QFN-10 (4mmx4mm)



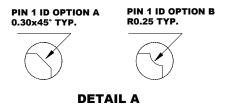


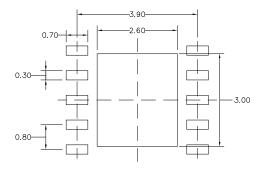
TOP VIEW

BOTTOM VIEW



SIDE VIEW





NOTE:

- 1) ALL DIMENSIONS ARE IN MILLIMETERS.
- 2) EXPOSED PADDLE SIZE DOES NOT **INCLUDE MOLD FLASH.**
- 3) LEAD COPLANARITY SHALL BE 0.10 **MILLIMETERS MAX.**
- 4) JEDEC REFERENCE IS MO-220.
- 5) DRAWING IS NOT TO SCALE.

RECOMMENDED LAND PATTERN

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